



Material Composition

Product GN1114-INE3, GN1114-INTE3D

Package QFN 24L 4 x 4 x 0.9

ID#54424.0

Manufacturer Gennum Corporation

Date 3/9/2010

Component	Subcomponent	Weight of Component mg	Substance	Weight of Substance mg	Homogeneous material	
					%	ppm
Leadframe	C94-FH	19.40	Cu	18.71	96%	964433
			Fe	0.46	2%	23711
			Zn	0.02	0%	1031
			P	0.02	0%	1031
			Ag	0.19	1%	9794
			Sub-total	19.40	100%	1000000
Mold compound	G770-HCD	21.93	Silica Fused	20.54	94%	936617
			Epoxy resin	0.66	3%	30096
			Phenolic resin	0.66	3%	30096
			Carbon black	0.07	0%	3192
			Sub-total	21.93	100%	1000000
Die	Silicon	1.27	Silicon	1.27	100.0%	1000000
			Sub-total	1.27	100%	1000000
Die Attach	CRM1076DS	0.20	Ag	0.15	74%	737101
			Epoxy resin	0.03	15%	147420
			Diluent	0.01	5%	49140
			Phenolics	0.01	5%	49140
			Dicyandiamide	0.00	0%	4914
			Epoxy silane	0.00	1%	12285
			Sub-total	0.20	100%	1000000
Wire	1.0 Mil AW66	0.61	Au	0.61	100%	1000000
			Impurities	0.00	0%	1641
			Sub-total	0.61	100%	1000000
External Plating	N/A	1.46	Sn	1.46	100%	1000000
			Sub-total	1.46	100%	1000000
Total		44.87				

GENNUM CORPORATION

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